AP5N20D

200V N-Channel Enhancement Mode MOSFET

Description

The AP5N20D is silicon N-channel Enhanced

VDMOSFETs, is obtained by the self-aligned planar Technology

which reduce the conduction loss, improve switching

 performance and enhance the avalanche energy. The transistor

can be used in various power switching circuit for system

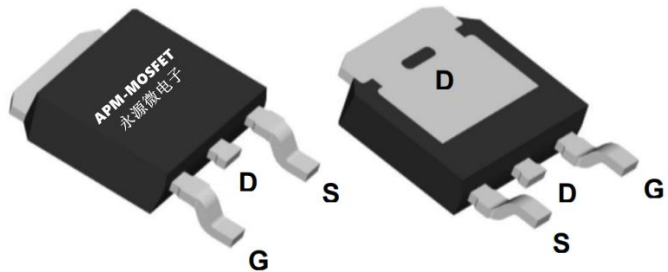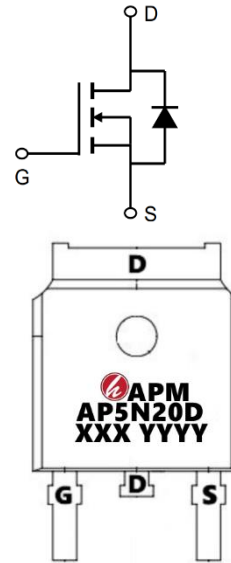miniaturization and higher efficiency.

General Features

VDS =200V,ID =5A

RDS(ON) <600mΩ@ VGS=10V **(Type：530mΩ)**

Application

Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP5N20D	TO-252-3L	AP5N20D XXX YYYY	2500

Absolute Maximum Ratings T_C = 25ºC, unless otherwise noted

Symbol	Parameter	Value	Unit
VDSS	Drain-Source Voltage (V_{GS} = 0V)	200	V
I_D	Continuous Drain Current	5	A
IDM	Pulsed Drain Current	20	A
VGSS	Gate-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy	45	mJ
IAR	Avalanche Current	3	A
E_{AR}	Repetitive Avalanche Energy	3.2	mJ
P_D	Power Dissipation (T_C = 25ºC)	46	W
RthJC	Thermal Resistance, Junction-to-Case	2.7	ºC/W
RthJA	Thermal Resistance, Junction-to-Ambient	60	ºC/W
TJ, Tstg	Operating Junction and Storage Temperature Range	-55~+150	ºC

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Electrical Characteristics (TJ=25℃, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA	200	221	--	V
IDSS	Zero Gate Voltage Drain Current	V_{DS} = 200V, V_{GS} = 0V, T_J = 25ºC	--	--	5	μA
IDSS		V_{DS} = 160V, V_{GS} = 0V, T_J = 125ºC	--	--	100	
IGSS	Gate-Source Leakage	V_{GS} = ±20V	--	--	±100	nA
VGS(th)	Gate-Source Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1.0	1.6	2.5	V
RDS(on)	Drain-Source On-Resistance (Note3)	V_{GS} = 10V, I_D = 2.5A	--	530	600	mΩ
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz	--	228	--	pF
C_{oss}	Output Capacitance		--	48	--	
C_{rss}	Reverse Transfer Capacitance		--	17	--	
Q_g	Total Gate Charge	V_{DD} = 160V, I_D = 5.0A, V_{GS} = 10V	--	18	--	nC
Q_{gs}	Gate-Source Charge		--	1.5	--	
Q_{gd}	Gate-Drain Charge		--	9.5	--	
td(on)	Turn-on Delay Time	V_{DD} = 100V, I_D = 5.0A, R_G = 25 Ω	--	10	--	ns
t_r	Turn-on Rise Time		--	19	--	
td(off)	Turn-off Delay Time		--	43	--	
t_f	Turn-off Fall Time		--	32	--	
I_S	Continuous Body Diode Current	T_C = 25 ºC	--	--	5	A
ISM	Pulsed Diode Forward Current		--	--	20	
V_{SD}	Body Diode Voltage	T_J = 25ºC, I_{SD} = 5A, V_{GS} = 0V	--	--	1.4	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0V, I_S = 5A, di_F/dt =100A /μs	--	160	--	ns
Q_{rr}	Reverse Recovery Charge		--	1.5	--	μC

Note :

1、The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2、The EAS data shows Max. rating . IAS = 3A, VDD = 50V, RG = 25 Ω, Starting TJ = 25 ºC

3、The test condition is Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%

4、The power dissipation is limited by 150℃ junction temperature

5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.
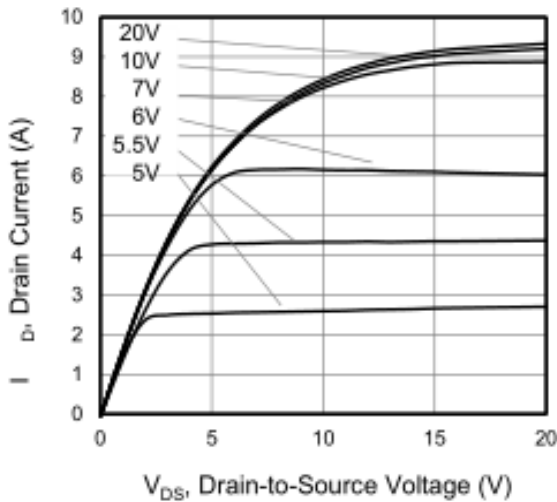
Typical Characteristics

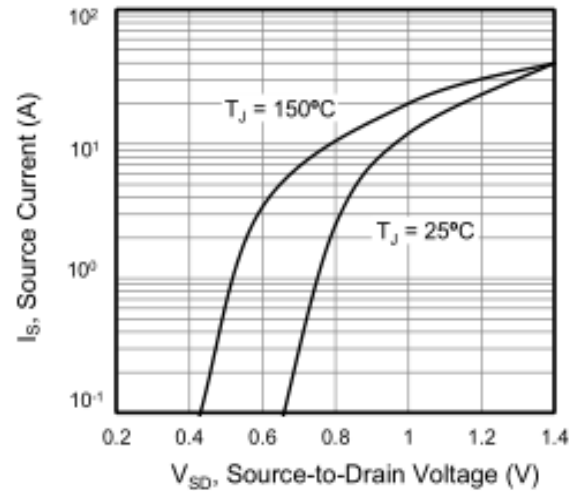**Figure 1. Output Characteristics (T$_J$ = 25ºC)**
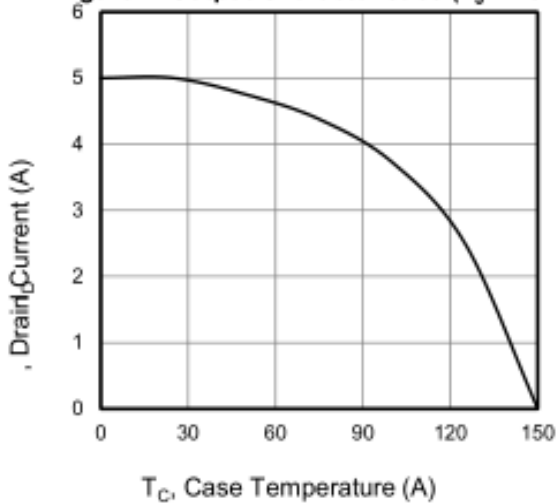

Figure 2. Body Diode Forward Voltage
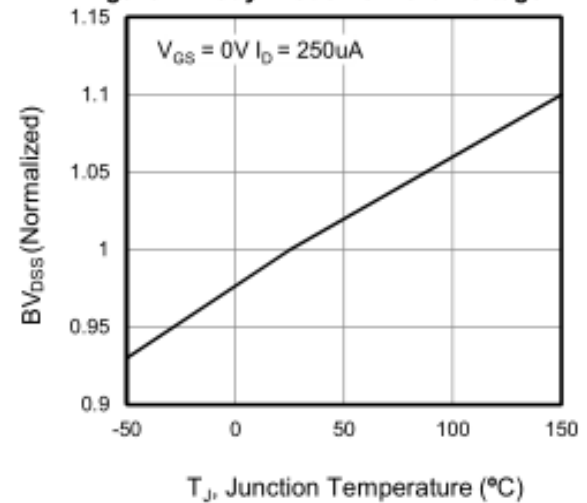

Figure 3. Drain Current vs. Temperature

Figure 4. BV$_{DSS}$ Variation vs. Temperature

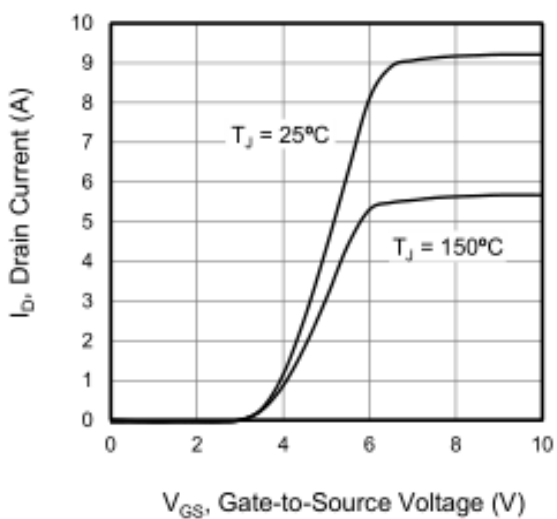**Figure 5. Transfer Characteristics**

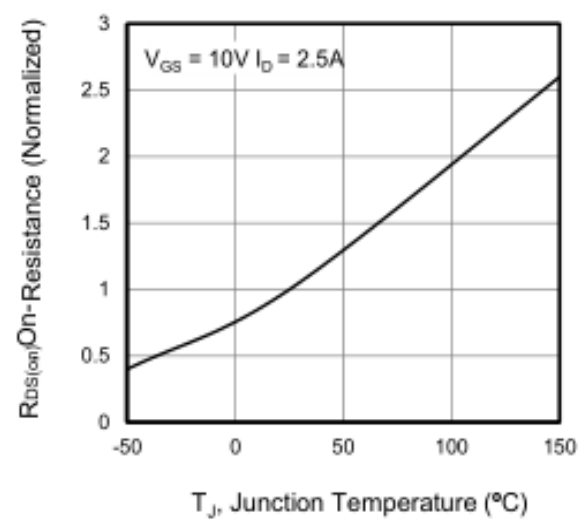**Figure 6. On-Resistance vs. Temperature**
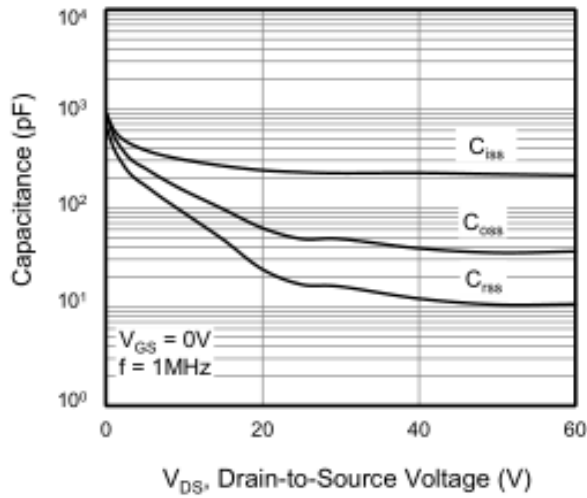
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Figure 7. Capacitance
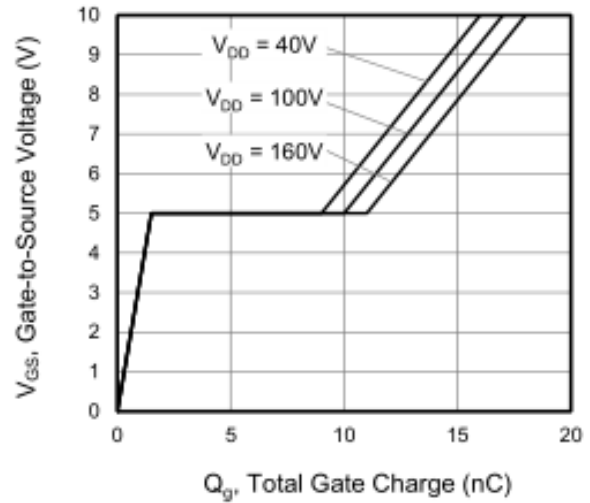
Figure 8. Gate Charge
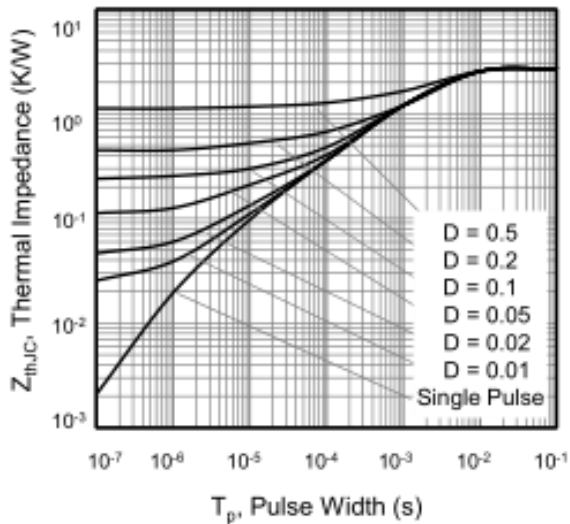
Figure 10. Transient Thermal Impedance

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Package Mechanical Data：TO-252-3L

TO-252
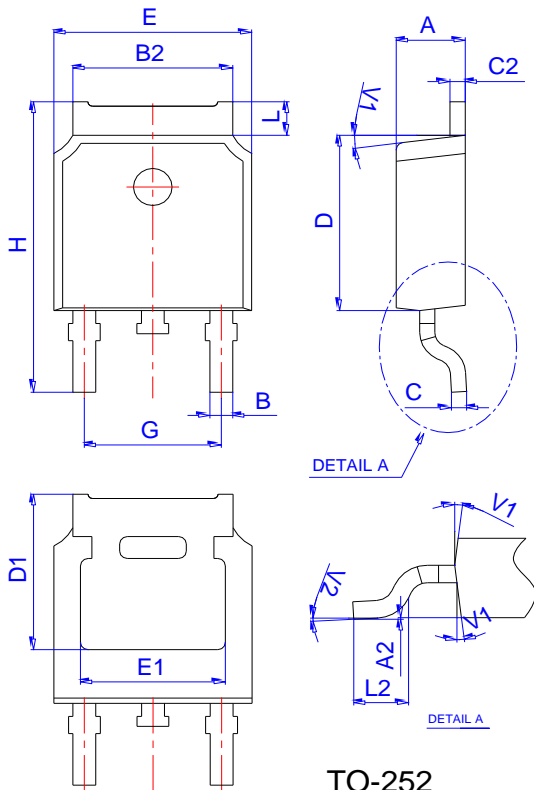
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO-252
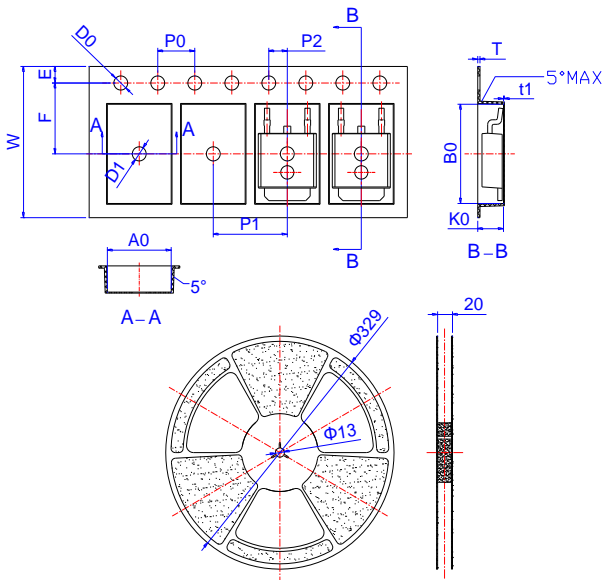
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

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Edition	Date	Change
Rve1.0	2020/5/31	Initial release

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